

Added claims 374-394:

372  
374. (Added) A structure comprising:

a first substrate comprising first electrical contact locations and a plurality of first elongated flexible electrical conductors extending from the first electrical contact locations;

a second substrate comprising second electrical contact locations on one side thereof and third contact locations on an opposite side thereof;

the second contact location facing the first contact locations, and each first elongated flexible electrical conductor comprises an end electrically connected to a first contact location, the second substrate being disassembleable from the first substrate, and second elongated flexible conductors having a first end electrically connected to a second contact location and extending away therefrom;

selected ones of the first elongated electrical conductors are electrically interconnected with selected ones of the second contact locations;

the first contact locations are spaced apart from one another by a first distance, the second contact locations are spaced apart from one another by a second distance.

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375. (Added) A structure, according to claim 374, wherein:

the second distance is different than the first distance.

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376. (Added) A structure, according to claim 374, wherein:

the second substrate comprises a printed circuit card.

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377. (Added) A structure, according to claim 374, wherein:

selected elements of the first and second plurality of elongated electrical conductors are embedded in a dielectric material.

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378. (Added) A structure, according to claim 374, wherein:

the first substrate is a printed circuit board.

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379. (Added) A structure, according to claim 374, wherein:

selected ones of the second electrical contact locations and selected ones of the third electrical contact locations are electrically interconnected by electrically conductive vias.

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380. (Added) A structure, according to claim 374, wherein an element selected from the group consisting of selected ones of the first and second flexible elongated electrical conductors comprise:


a flexible elongate core element having a first end and a second end and formed of a readily-shaped material;

an electrically conductive coating, formed of a layer of conductive material disposed on the elongate core element.

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~~381.~~ (Added) A structure, according to claim 380, wherein:

the flexible elongate core element is selected from the group consisting of:

palladium, gold alloy, copper alloy, gold, aluminum, copper, silver, nickel and combinations thereof.

  
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~~382.~~ (Added) A structure, according to claim 380, wherein:

the flexible elongate core element has a diameter in the range of from 1 to 5 mils.

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~~383.~~ (Added) A structure, according to claim 382, wherein:

the flexible elongate core element is a wire.

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~~384.~~ (Added) A structure, according to claim 380, wherein:

the flexible elongate core element has a length of about 40 mils.

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~~385.~~ (Added) A structure, according to claim 380, wherein:

the electrically conductive coating comprising a material selected from the group consisting of Au, Cr, Co, Ni and Pd.

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~~386.~~ (Added) A structure, according to claim 380, wherein:

the electrically conductive coating comprises nickel and cobalt.

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387. (Added) A structure, according to claim 380, wherein:

the electrically conductive coating comprises a coating selected from the group consisting of nickel, cobalt, chromium, gold and palladium.

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388. (Added) A structure, according to claim 380, wherein:

the electrically conductive coating is formed of a material selected from nickel, cobalt, chromium and gold.

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389. (Added) A structure, according to claim 380, wherein:

the electrically conductive coating is a coating selected from the group consisting of an electroplated coating, an electrolessly plated coating, a sputtered coating and an e-beam evaporated coating.

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390. (Added) A structure, according to claim 389, wherein:

the electrically conductive coating is a thin layer.

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391. (Added) A structure, according to claim 374, wherein:

an element selected from the group consisting of the first and the second substrate is a multi-layer interconnection substrate.

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392. (Added) A structure, according to claim 374, wherein:

the second substrate comprises a fan out substrate.

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393. (Added) A structure, according to claim 374, wherein:

the first and second elongated electrical conductors are embedded in a dielectric layer and the second substrate is a fan out substrate.

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394. (Added) A structure, according to claim 393, wherein:

the first elongated electrical conductors embedded in the dielectric layer comprise an interposer disposed between the first and second substrate to provide electrical connection between selected ones of the first electrical contact locations and selected ones of the second electrical contact location through selected ones of the first elongated electrical conductors.

#### REMARKS

Support for the added claims 374-394 is found throughout the specification and in US application serial number 07/685,368 filed on Oct. 19, 1992 incorporated by reference at page 7, lines 6-8 from the bottom, now issued as US 5,371,654 on December 6, 1994.

Claims 374-394 added herein are substantially identical to the claims of US 6,274,823 B1 which has an earliest claimed priority date of November 16, 1993. The present application is a continuation of US Application Serial Number 08/872,579, filed on 6/11/1997, now Issued as US 6,334,247 B1 which is a divisional of US Application Serial Number 08/754,869, filed on November 22, 1996, now issued as US 5,821,763 on October 13, 1998, which is a continuation of US Application Serial Number 08/055,485, filed on April 30, 1993 and now issued as US 5,635,846 on June 3, 1997. Therefore, US 5,371,654 and US 5,635,846 are both 35 USC 102(e) references against US 6,274,823 B1.